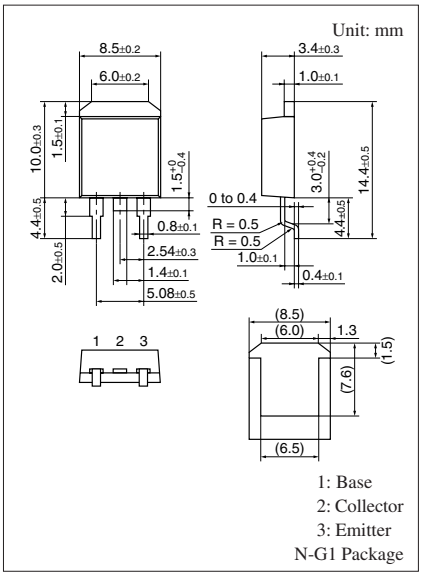
2SB1070, 2SB1070A

Silicon PNP epitaxial planar type

For low-voltage switching

■ Features

- Low collector-emitter saturation voltage $V_{CE(sat)}$
- High-speed switching
- N type package enabling direct soldering of the radiating fin to the printed circuit board, etc. of small electronic equipment



Note) Self-supported type package is also prepared.

■ Absolute Maximum Ratings $T_C = 25°C$

Parameter		Symbol	Rating	Unit
Collector-base voltage (Emitter open)	2SB1070	V_{CBO}	−40	V
	2SB1070A		−50	
Collector-emitter voltage (Base open)	2SB1070	V_{CEO}	−20	V
	2SB1070A		−40	
Emitter-base voltage (Collector open)		V_{EBO}	−5	V
Collector current		I_C	−4	A
Peak collector current		I_{CP}	−8	A
Collector power dissipation		P_C	25	W
	$T_a = 25°C$		1.3	
Junction temperature		T_j	150	°C
Storage temperature		T_{stg}	−55 to +150	°C

■ Electrical Characteristics $T_C = 25°C \pm 3°C$

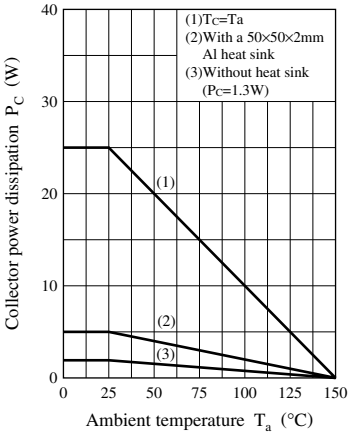
Parameter		Symbol	Conditions	Min	Typ	Max	Unit
Collector-emitter voltage (Base open)	2SB1070	V_{CEO}	$I_C = -10$ mA, $I_B = 0$	−20			V
	2SB1070A			−40			
Collector-base cutoff current (Emitter open)	2SB1070	I_{CBO}	$V_{CB} = -40$ V, $I_E = 0$			−50	μA
	2SB1070A		$V_{CB} = -50$ V, $I_E = 0$			−50	
Emitter-base cutoff current (Collector open)		I_{EBO}	$V_{EB} = -5$ V, $I_C = 0$			−50	μA
Forward current transfer ratio		h_{FE1}	$V_{CE} = -2$ V, $I_C = -0.1$ A	45			—
		h_{FE2} *	$V_{CE} = -2$ V, $I_C = -1$ A	90		260	
Base-emitter saturation voltage		$V_{BE(sat)}$	$I_C = -2$ A, $I_B = -0.1$ A			−1.5	V
Collector-emitter saturation voltage		$V_{CE(sat)}$	$I_C = -2$ A, $I_B = -0.1$ A			−0.5	V
Transition frequency		f_T	$V_{CE} = -5$ V, $I_C = -0.5$ A, f = 10 MHz		150		MHz
Turn-on time		t_{on}	$I_C = -2$ A		0.3		μs
Storage time		t_{stg}	$I_{B1} = -0.2$ A, $I_{B2} = 0.2$ A		0.4		μs
Fall time		t_f	$V_{CC} = -20$ V		0.1		μs

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

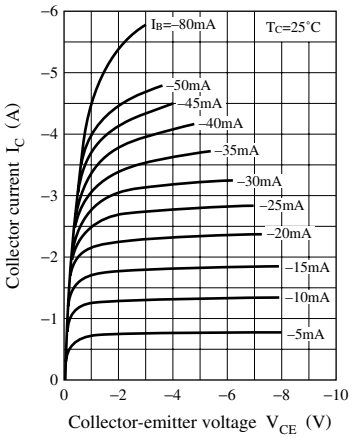
2. *: Rank classification

Rank	Q	P
h_{FE2}	90 to 180	130 to 260

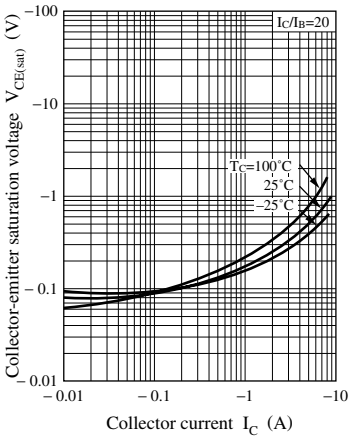
P_C — T_a



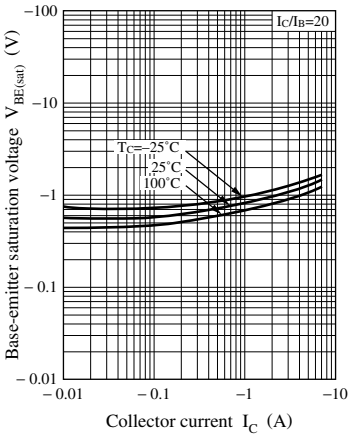
I_C — V_{CE}



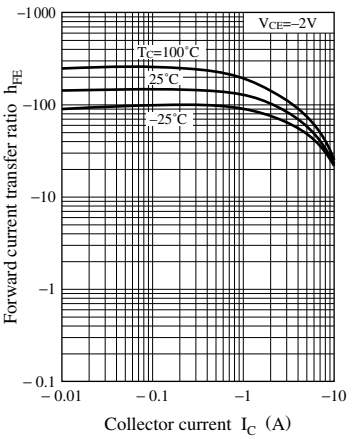
$V_{CE(sat)}$ — I_C



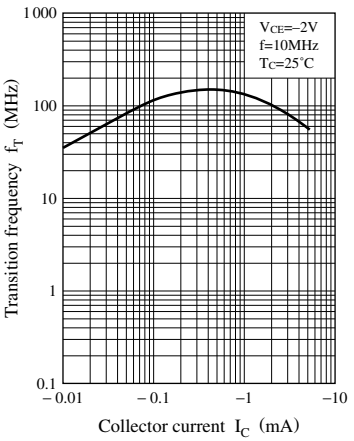
$V_{BE(sat)}$ — I_C



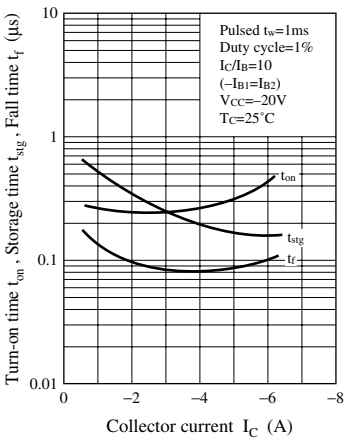
h_{FE} — I_C



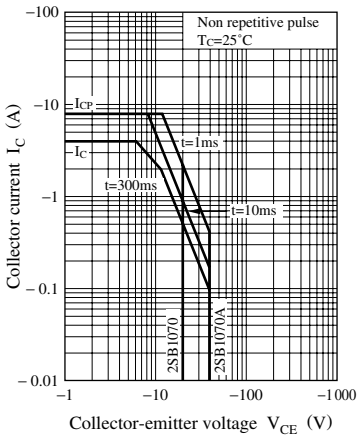
f_T — I_C

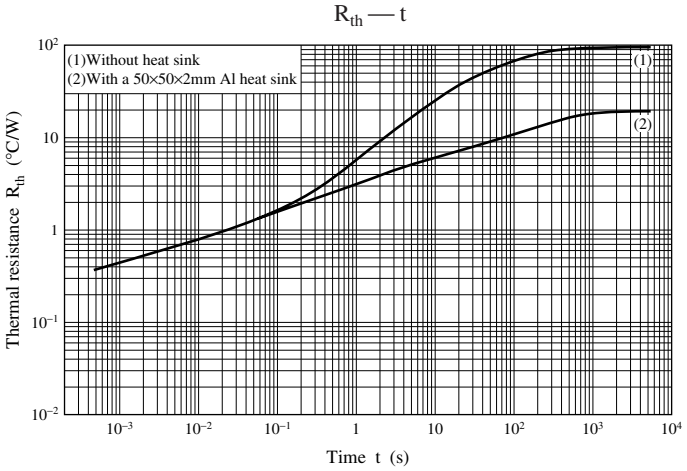


t_{on} , t_{stg} , t_f — I_C



Safe operation area




R_{th} — t
(1)Without heat sink
(2)With a 50×50×2mm Al heat sink
(1)
(2)
Thermal resistance R_{th} (°C/W)
10^2
10
1
10^{-1}
10^{-2}
10^{-3}
10^{-2}
10^{-1}
1
10
10^2
10^3
10^4
Time t (s)

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